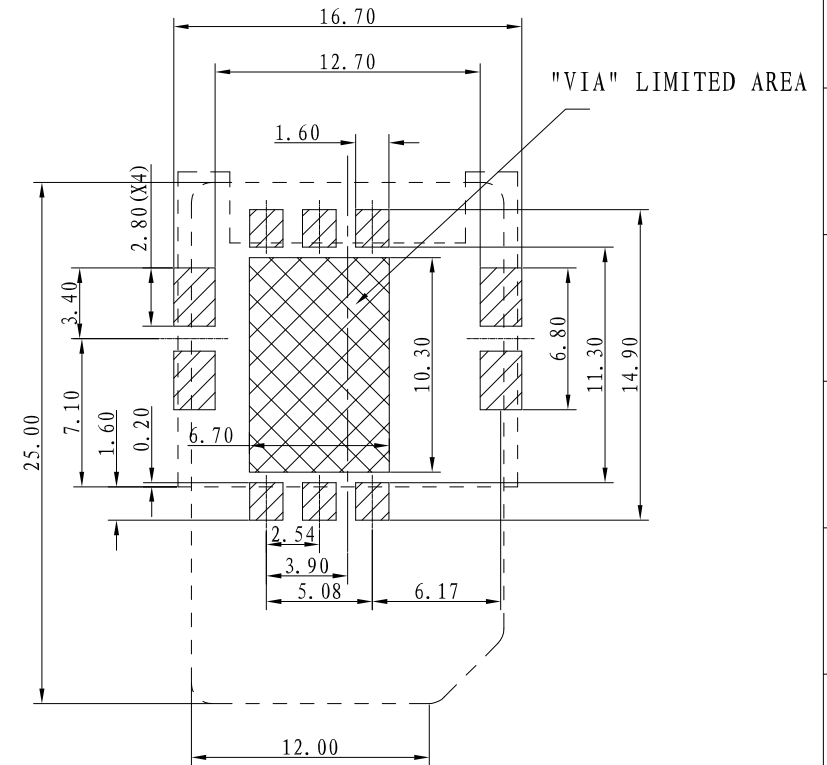
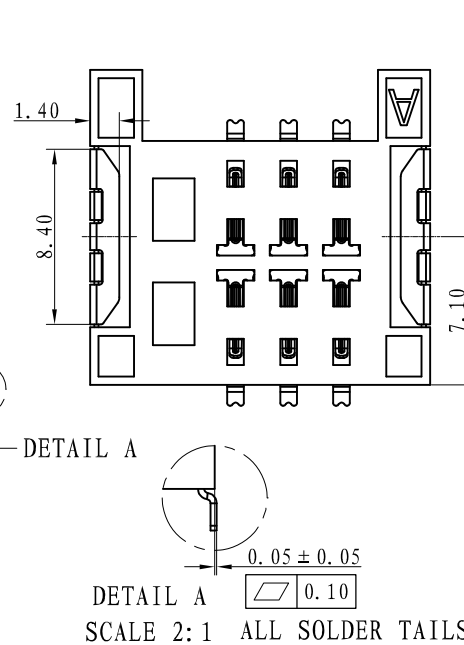
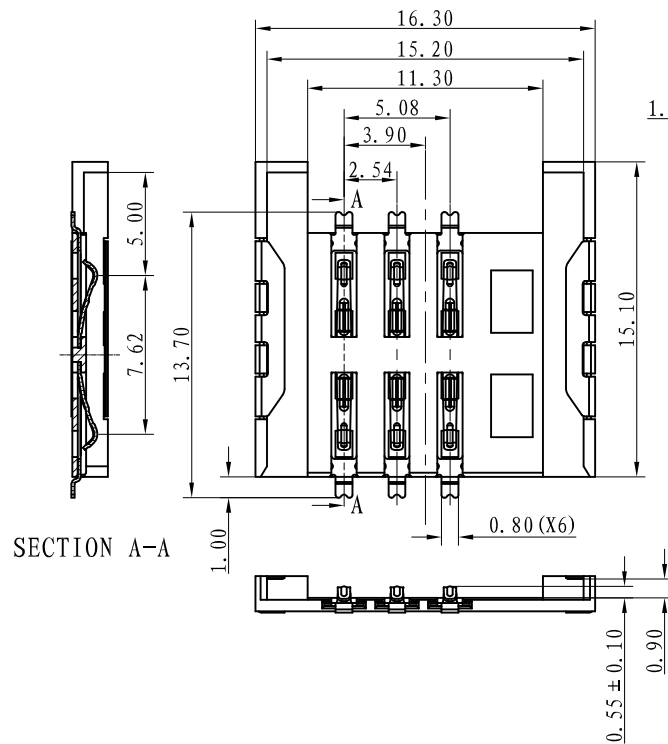


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
AO		NEW RELEASE	2016.06.15	YANG		WEI



RECOMMENDED PCB LAYOUT
TOLERANCE: ± 0.05

NOTES:

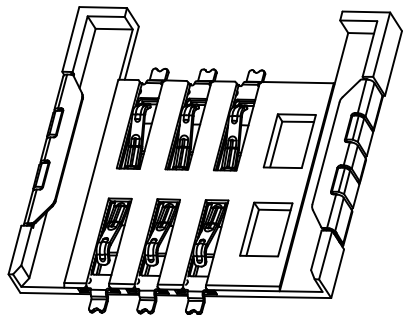
1. MATERIAL:

- 1.1. HOUSING: HI-TEMP PLASTIC,UL94V-0,BLACK
- 1.2. TERMINAL: COPPER ALLOY,T=0.15mm
- 1.3. LATCH: STAINLESS STEEL,T=0.15mm

2. FINISH :

- 2.1. TERMIANL: PLATED AU OVER ALL,
UNDERPLATED NICKEL.
- 2.2. LATCH: PLATED AU OVER ALL,
UNDERPLATED NICKEL.

3. OP. Temperature: $-40^{\circ}\text{C}\sim+85^{\circ}\text{C}$



MILLIMETERS	INCH	UNITS	MM	东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.			
X° ± 2'	X° ± 2'	MAT'L		PART NUMBER: XB-102011262			
.X ± 0.30	.XX ± 0.012	SEE NOTES		TITLE: SIM CARD 6P H1.7			
.XX ± 0.20	.XXX ± 0.008	FINISH		APPD: WEI			
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES		DWG NO.: C-102011262-00			
				CHKD: Yang			
				DR: Yang			
				SCALE: 1:1			
				SHEET: 1/2			
				REV: A0			

